

CLAIMS

1. ~~An adhesive label characterized by comprising~~ a circuit substrate, electronic components formed on one surface of said circuit substrate, and an adhesive layer on said electronic components for applying to an article, which are sequentially laminated.

2. The adhesive label according to claim 1, wherein said adhesive layer is a pressure sensitive adhesive layer.

3. The adhesive label according to claim 1, wherein said adhesive layer is a double-coated adhesive layer having an adhesive layer on each side of a support sheet.

4. The adhesive label according to any one of claims 1 to 3, wherein an entire contactless data carrier element containing said electronic components is carried on one side of said circuit substrate, and said adhesive layer for applying on an article is formed <sup>over</sup> on said entire contactless data carrier element.

5. The adhesive label according to any one of claims 1 to 4, wherein a surface layer is provided on a circuit substrate surface that is <sup>on the</sup> a reverse side to a surface carrying said electronic components.

6. The adhesive label according to claim 5, wherein electronic components are separately formed on each surface of said circuit substrate and connected with each other by a through-hole to integrate both electronic components to form an entire contactless data carrier element, said adhesive layer for applying to an article is formed on one of said separately formed electronic components, and said surface layer is formed on the other of said separately formed electronic components.